NearStack HD Connector System >

The NearStack HD Connector System is a low-profile, high-density cable solution with a 64 Gbps PAM-4 data transfer rate that meets PCIe Gen-6 standards for internal cable applications and helps users support artificial intelligence (AI) and machine learning applications.

ADVANTAGES AND FEATURES

Maximizes real estate in high-density applications

with a low-profile connector that optimizes PCB real estate for space-constrained applications, including angled-exit options that reduce connector spacing from 20.50 to 16.00mm on center

Enhances signal integrity (SI) with direct-to-contact termination

featuring twinax wires welded directly to the signal contact wafers within the connector, which improves SI and delivers best-in-class crosstalk performance

Simplifies assembly and makes the connector more durable

with direct-to-contact termination that eliminates the need for a paddle card interface

Improves thermal performance

using small 34 AWG twinax cable that allows for better airflow, improving thermal management

Data Rate

Wire Size

Height

Cable Lengths

Offers greater design flexibility

with 34 AWG twinax cable that afford easier cable routing compared to 30 AWG

Enables PCIe Gen-6 performance for AI and machine learning capabilities

with data rates of up to 64 Gbps PAM-4 that meet PCIe Gen-6 specifications and permit data centers to achieve next-generation performance

Storage Devices

Networking Devices



APPLICATIONS

Server and Storage

Data centers Storage devices Servers and machine learning Al infrastructure

Telecommunications

Al systems Networking devices High-performance computing Device control units





PCIe Gen-6 (up to 64 Gbps PAM-4)

85 Ohms

56 (18 differential pairs)

34 AWG twinax

9.50mm

110mm to 1.0m



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SPECIFICATIONS

Reference Information

Product Series:

NearStack HD PCB Header - 215980 NearStack HD Right-Angle Exit Cable Assembly - 216000 NearStack HD Angled-Exit Cable Assembly - 221028 Packaging: Tape and reel Designed in: Millimeters RoHS: Yes Halogen Free: Yes

Electrical

Voltage (max.): 29.9V RMS
Current (max.): 0.65A per mated contact pair, no grouping restrictions
Contact Resistance: 20 milliohms max. (from initial)
Dielectric Withstanding Voltage: 1,000V AC RMS
Insulation Resistance: 1,000 Megohms
Signal Continuity: No interrupts greater than 1 microsecond

Environmental

Temperature Rise: 0.25A through 8 adjacent circuits, with a max. temp. rise of 30°C Temperature Life: EIA-364-17 method A cond. 4 Thermal Shock: EIA-364-32 method A cond. 1

Cyclic Temperature and Humidity: EIA-364-31 method III

Mixed Flowing Gas: EIA-364-65 class IA option 2 Thermal Disturbance: EIA-364-110 cond. A duration A Dust: EIA-364-91

Mechanical

Mating Force: 2N max. per differential pair Unmating Force: 30N Durability (min.): 100 cycles Wafer Retention Force (Plug): 1.0N min. per married wafer set

Normal Force: 30N min. per signal contact Mechanical Vibration: EIA-364-28 cond. VII Mechanical Shock: EIA-364-27 method A

Physical

Housing: LCP Wafers: LCP and Copper Alloy Plug Shell: Stainless Steel Plug Vacuum Cap: LCP Receptacle Cover: LCP Receptacle Top and Bottom Retainers: Polycarbonate (clear) Receptacle Latch: Stainless Steel Receptacle Protective Cover: Polypropylene (PMS Blue 2192C) Contact: Copper Plating: Contact Area – 0.76µm over 1.72µm Nickel overall SMT Tail Area – 2.54µm Selective Tin over 1.27µm Nickel overall Operating Temperatures: -40 to +85°C

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